

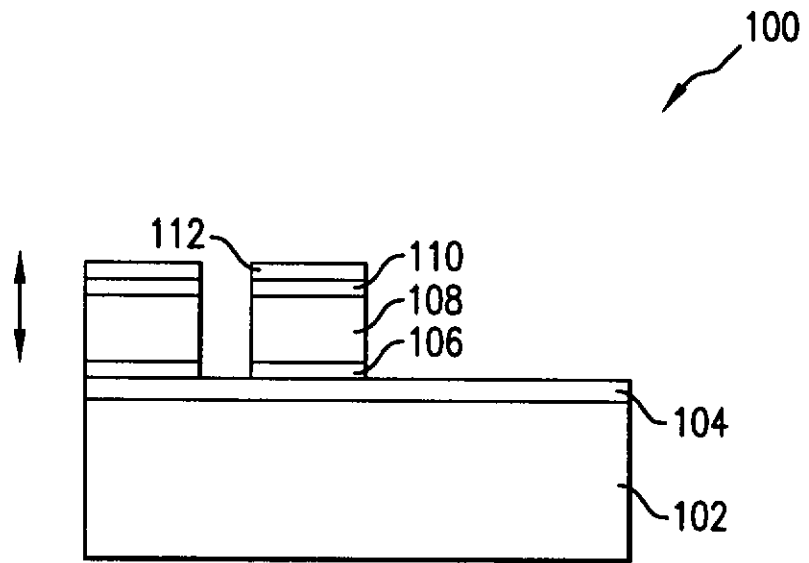


FIG. 1

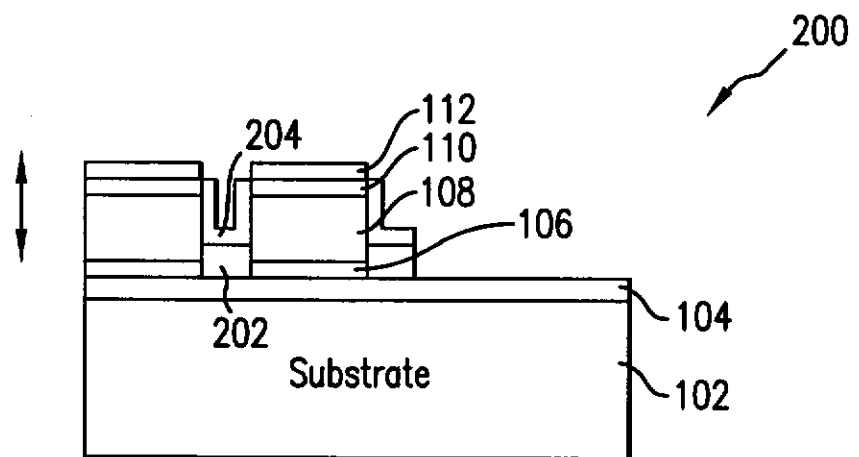


FIG. 2

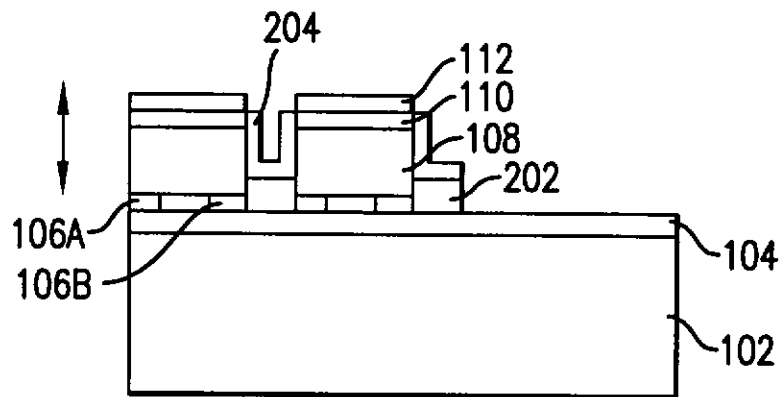


FIG. 3

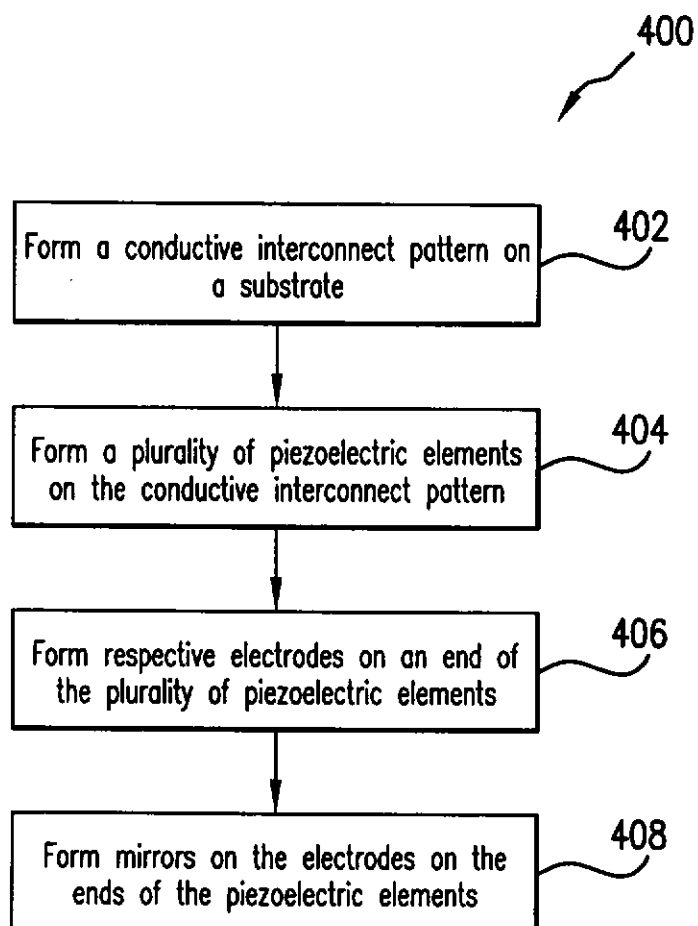


FIG. 4

3/5

500

402

Plate a substrate with an interconnect pattern with a suitable conductor to provide a first array of electrodes

502

404

Deposit a film of PZT material

504

406

Deposit a top conductor layer to provide ground plane connections for actuator elements

506

Deposit materials used to form reflective devices

508

Coat the material for the reflective devices with resist

510

Expose the resist with a reflector pattern

512

Develop the resist

514

Expose the mirror layers to be etched

516

Remove the remaining resist

518

Perform a lapping operation to provide a flat surface with actuator pattern therein

520

Package and/or Bond the SLM

522

408

FIG. 5

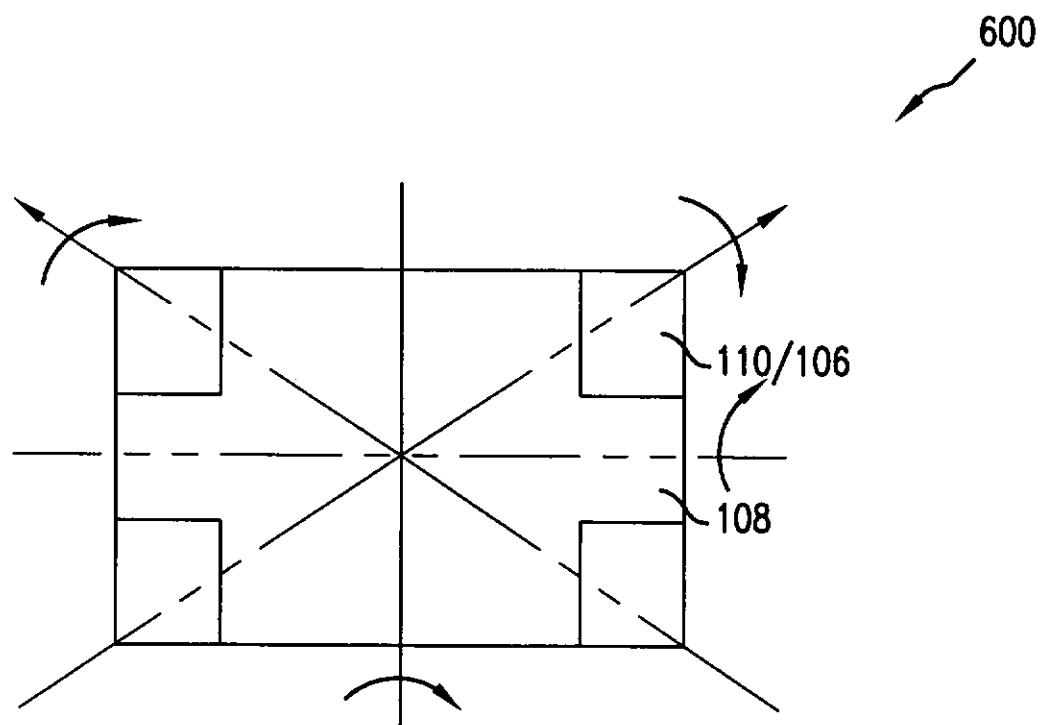


FIG. 6

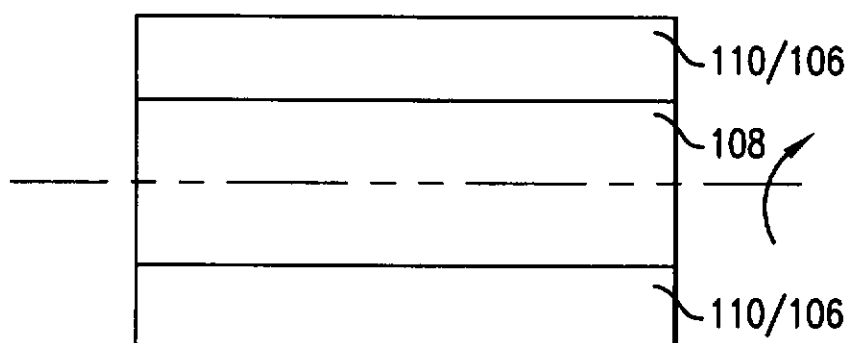


FIG. 7

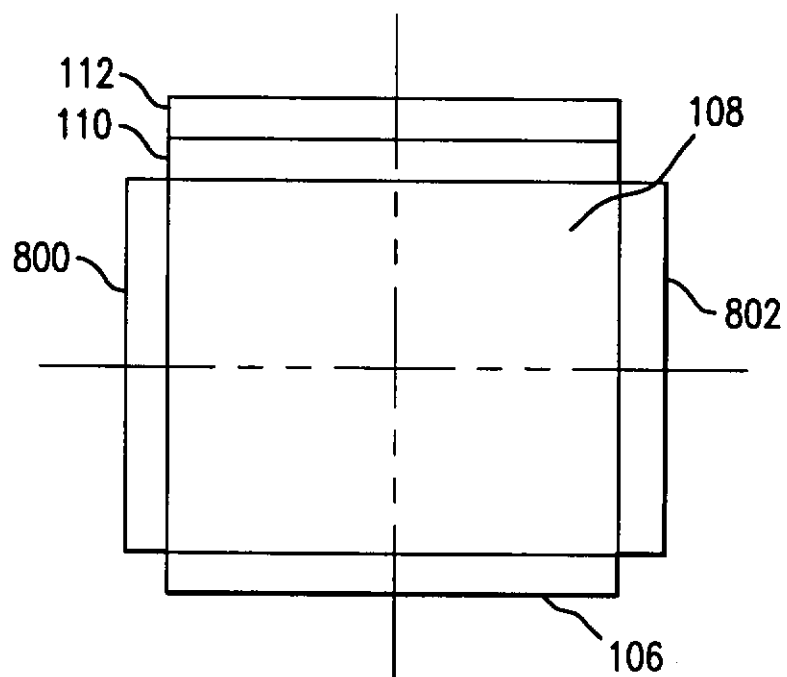


FIG. 8

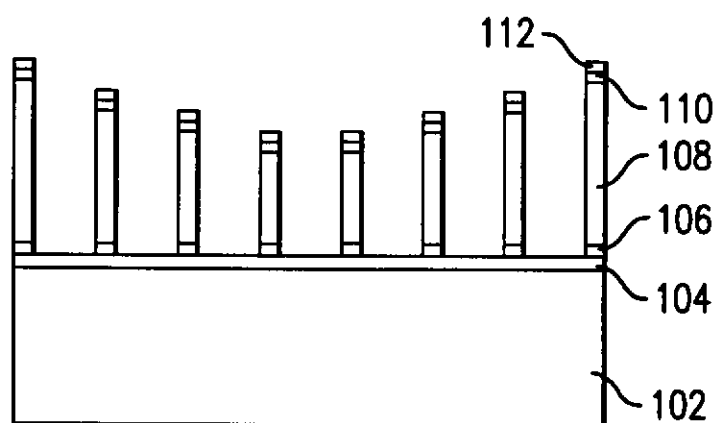


FIG. 9